



Application No. 10/771,451

Docket No.: N0029.1650

**AMENDMENTS TO THE SPECIFICATION**

Please amend the paragraph at page 3, lines 10-21 as follows:

If a photosensitive resin is used in direct contact with the semiconductor chip, however, it is difficult to ensure reliability over a long term of use because the temperature of the semiconductor chip can reach ~~[[60? C]]~~ 60°C or more during use. When considering that there is a tendency of increase in the amount of heat that is generated per unit surface area of the semiconductor chip as the chip size is made smaller and the chip is given higher functionality, this manufacturing method cannot contribute to making the semiconductor chip smaller, and cannot contribute to giving the connection pads on the semiconductor chip a more narrower pitch.